

# Four Output PCI-X and General Purpose Buffer

#### **Features**

- One input to four output buffer/driver
- General-purpose or PCI-X clock buffer
- Buffers all frequencies from DC to 140 MHz
- Output-to-output skew less than 100 ps
- Space-saving 8-pin TSSOP package
- 3.3 V operation
- 60 ps typical output-output skew

# **Functional Description**

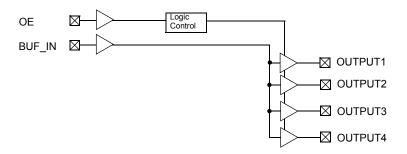
The CY2304NZ is a low-cost buffer designed to distribute high-speed clocks for PCI-X and other applications. The device operates at 3.3 V and outputs can run up to 140 MHz.

For a complete list of related documentation, click here.

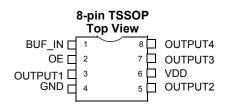
#### **Function Table**

Inp	Outputs	
BUF_IN	OE	Output [1:4]
L	L	L
Н	L	L
L	Н	L
Н	Н	Н

# **Block Diagram**



# **Pin Configuration**



# **Pin Description**

For CY2304NZ

Signal	Pin	Description	
$V_{DD}$	6	3.3 V voltage supply	
GND	4	Ground	
BUF_IN	1	Input clock	
OUTPUT [1:4]	3, 5, 7, 8	Outputs	
OE	2	Input pin for output enable, active HIGH.	



# **Maximum Ratings**

Supply Voltage to Ground Potential .... –0.5 V to  $\mathrm{V}_\mathrm{DD}$  + 0.5 V DC Input Voltage ......–0.5 V to  $V_{DD}$  + 0.5 V

Storage Temperature	–65 °C to +150 °C
Max. Soldering Temperature (10 sec.)	260 °C
Junction Temperature	150 °C

# **Operating Conditions**

Parameter	Description	Min	Max	Unit
$V_{DD}$	Supply Voltage	3.0	3.6	V
T <sub>A</sub>	Operating Temperature (Ambient Temperature)	-40	85	°C
C <sub>L</sub>	Load Capacitance	_	25	pF
C <sub>IN</sub>	Input Capacitance	_	7	pF
BUF_IN, OUTPUT [1:4]	Operating Frequency	DC	140	MHz
t <sub>PU</sub> <sup>[1]</sup>	Power-up time for all VDD's to reach minimum specified voltage (power ramps must be monotonic)	0.05	50	ms

# **Electrical Characteristics**

Parameter	Description	Test Conditions	Min	Max	Unit
V <sub>IL</sub>	Input LOW Voltage [2]		_	0.8	V
V <sub>IH</sub>	Input HIGH Voltage [2]		2.0	-	V
I <sub>IL</sub>	Input LOW Current	V <sub>IN</sub> = 0 V	-5	5	μА
I <sub>IH</sub>	Input HIGH Current	$V_{IN} = V_{DD}$	-5	5	μА
V <sub>OL</sub>	Output LOW Voltage [3]	I <sub>OL</sub> = 24 mA	_	0.8	V
		I <sub>OL</sub> = 12 mA	_	0.55	V
V <sub>OH</sub>	Output HIGH Voltage [3]	I <sub>OH</sub> = –24 mA	2.0	-	V
		I <sub>OH</sub> = -12 mA	2.4	_	V
I <sub>DD</sub>	Supply Current	Unloaded outputs at 66.66 MHz	_	25	mA

# **Thermal Resistance**

Parameter [4]	Description	Test Conditions	8-pin TSSOP	Unit
U/A	10	Test conditions follow standard test methods and procedures for measuring thermal impedance, in		°C/W
$\theta_{JC}$	Thermal resistance (junction to case)	accordance with EIA/JESD51.	33	°C/W

- This operating condition guarantees skew and propagation delay.
   BUF\_IN input has a threshold voltage of V<sub>DD</sub>/2.
   Parameter is guaranteed by design and characterization. It is not 100% tested in production.
- 4. These parameters are guaranteed by design and are not tested.

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# **Switching Characteristics**

For Commercial and Industrial Temperature Devices which are characterized over the frequency range of 1 MHz to 140 MHz.

Parameter [5]	Name	Description	Min	Тур	Max	Unit
	Duty Cycle [6] = t <sub>2</sub> ÷ t <sub>1</sub>	Measured at 1.5 V	40.0	50.0	60.0	%
t <sub>3</sub>	Rise Time [6]	Measured between 0.8 V and 2.0 V	_	_	1.50	ns
t <sub>4</sub>	Fall Time [6]	Measured between 0.8 V and 2.0 V	_	_	1.50	ns
t <sub>5</sub>	Output to Output Skew [6]	All outputs equally loaded	_	60	100	ps
t <sub>6</sub>	Propagation Delay, BUF_IN Rising Edge to OUTPUT Rising Edge <sup>[6]</sup>	Measured at V <sub>DD</sub> /2	2.5	3.5	5	ns

# **Switching Waveforms**

Figure 1. Duty Cycle Timing

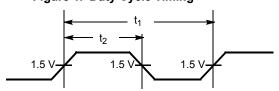


Figure 2. All Outputs Rise/Fall Time

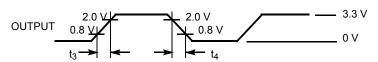


Figure 3. Output-Output Skew

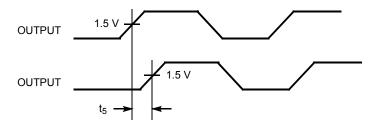
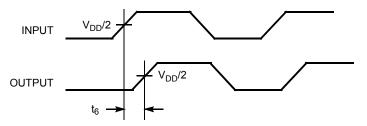


Figure 4. Input-Output Propagation Delay



#### Notes

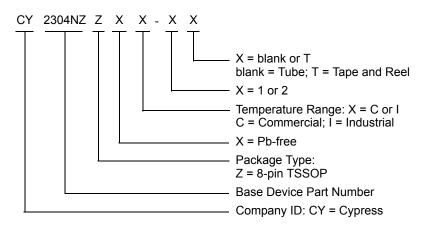
- 5. All parameters specified with loaded outputs.6. Parameter is guaranteed by design and characterization. It is not 100% tested in production.



# **Ordering Information**

Ordering Code	Package Type	Operating Range
Standard	·	
CY2304NZZI-1	8-pin TSSOP	Industrial, –40 °C to 85 °C
CY2304NZZI-1T	8-pin TSSOP – Tape and Reel	Industrial, –40 °C to 85 °C
Pb-free	·	•
CY2304NZZXC-1	8-pin TSSOP	Commercial, 0 °C to 70 °C
CY2304NZZXC-1T	8-pin TSSOP – Tape and Reel	Commercial, 0 °C to 70 °C
CY2304NZZXI-1	8-pin TSSOP	Industrial, –40 °C to 85 °C
CY2304NZZXI-1T	8-pin TSSOP – Tape and Reel Industrial, –40 °C to 85 °C	

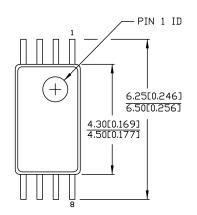
# **Ordering Code Definitions**





# **Package Diagram**

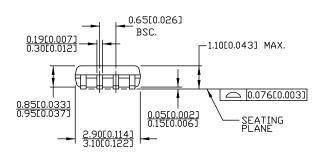
Figure 5. 8-pin TSSOP (4.40 mm Body) Z08.173/ZZ08.173 Package Outline, 51-85093

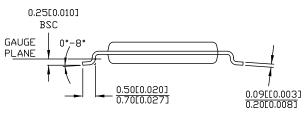


DIMENSIONS IN MM(INCHES) MIN. MAX.

REFERENCE JEDEC MD-153

PART #		
Z08.173 STANDARD PKG.		
ZZ08.173	LEAD FREE PKG.	





51-85093 \*E

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# **Acronyms**

Acronym	Description
PCI	Peripheral Component Interconnect
TSSOP	Thin-Shrink Small Outline Package

# **Document Conventions**

# **Units of Measure**

Symbol	Unit of Measure
°C	degree Celsius
Hz	hertz
MHz	megahertz
μΑ	microampere
mA	milliampere
ms	millisecond
mV	millivolt
ns	nanosecond
Ω	ohm
%	percent
pF	picofarad
ps	picosecond
V	volt
W	watt



# **Document History Page**

Rev.	ECN No.	Issue Date	Orig. of Change	Description of Change
**	111420	02/12/02	IKA	New data sheet.
*A	118610	09/25/02	HWT	Updated Ordering Information: Added Industrial Temperature Range in the Ordering Information.
*B	121820	12/14/02	RBI	Updated Operating Conditions: Added t <sub>PU</sub> parameter and its details.
*C	291098	See ECN	RGL	Updated Switching Characteristics: Specified typical value for "Output to Output Skew" parameter. Updated Ordering Information: Added Lead-free Devices.
*D	2904623	04/05/10	CXQ	Updated Ordering Information (Removed inactive parts). Updated Package Diagram.
*E	3163624	02/05/2011	CXQ	Updated Maximum Ratings (Removed reference to "Except REF" and "REF for DC Input Voltage spec).  Added Ordering Code Definitions.  Updated Package Diagram.  Added Acronyms and Units of Measure.  Updated to new template.
*F	3931498	04/08/2013	· · · · · · · · · · · · · · · · · · ·	
*G	4103402	08/23/2013	MNSB	Updated Operating Conditions: Added Note 1 and referred the same note in t <sub>PU</sub> parameter. Updated to new template.
*H	4312848	03/18/2014	CINM	No technical updates. Completing Sunset Review.
*	4578443	11/25/2014	AJU	Updated Functional Description: Added "For a complete list of related documentation, click here." at the end Updated Package Diagram: spec 51-85093 – Changed revision from *D to *E.
*J	4756553	05/06/2015	TAVA	Updated Switching Characteristics: Replaced "For Commercial and Industrial Temperature Devices" with "For Commercial and Industrial Temperature Devices which are characterized ov the frequency range of 1 MHz to 140 MHz." for characterization.
*K	5258800	05/04/2016	PSR	Added Thermal Resistance. Updated to new template.



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